
Understanding of SKIROC performance

T. Frisson (LAL)
On behalf of the SiW ECAL team

Special thanks to the electronic and DAQ experts:
Stéphane Callier, Rémi Cornat and Frédéric Magniette
And to:
Romain De Abreu (Internship student)

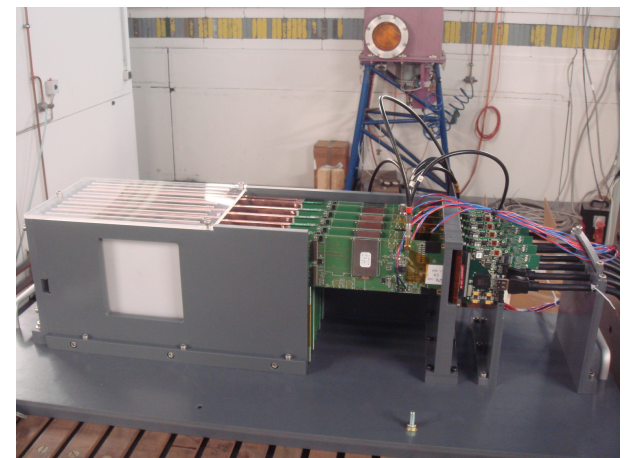
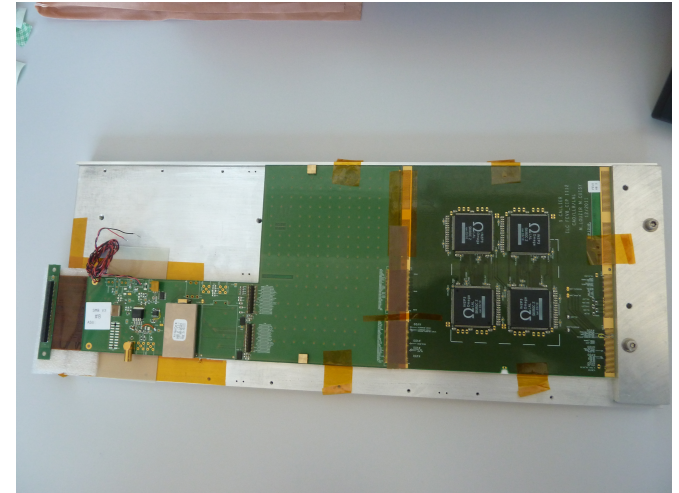
The road to the technological prototype

Intermediate step: { First test in beam
Benchmark to go further

- U structure (single detection layer per slab)
- Si wafer:
 - 9x9 cm² – Thickness = 320 μm
 - **pixel size: 5x5 mm²** :lateral granularity = 4 x better than physics prototype
- 4 SKIROCs per slab (1/4 final design)
 - 4 x 64 channels = 256 channels/slab

DESY : e- (1 - 5 GeV)

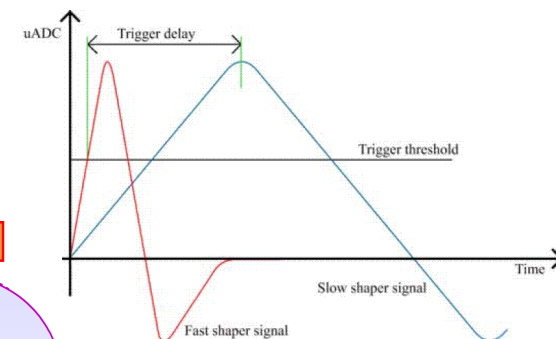
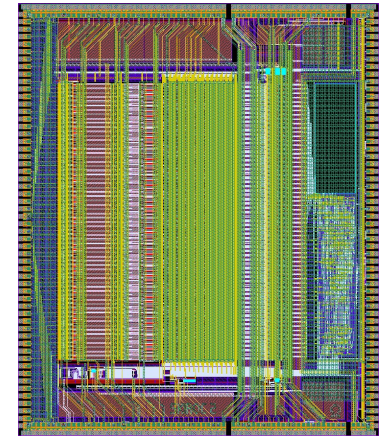
- Spring 2012 : 1 layer
- Summer 2012 : 6 layers
- Winter 2013 : 10 layers (see Vladik and Yuji talks)



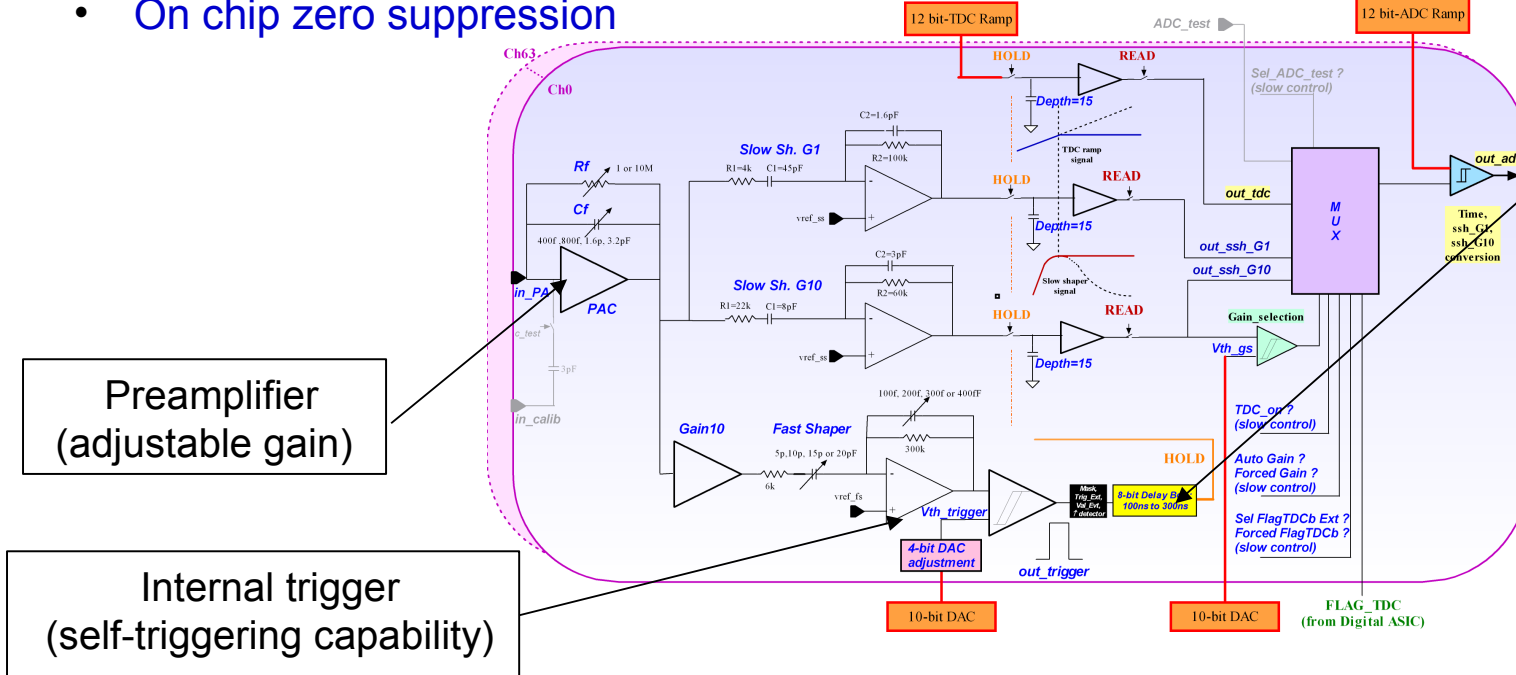
Front end electronics: SKIROC

SKIROC (Silicon Kalorimeter Integrated Read Out Chip)

- SiGe 0.35 μ m AMS
- 7.5 mm x 8.7 mm
- High integration level (variable gain charge amp, 12-bit ADC, digital logic)
- 64 channels
- Large dynamic range (~2500 MIPS), low noise (0.4 fC – 10 pC)
- Auto-trigger at 1/2 MIP
- Low Power: (25 μ W/ch) power pulsing
- On chip zero suppression



Trigger delay



Preamplifier
(adjustable gain)

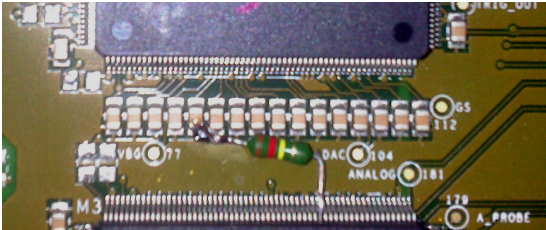
Internal trigger
(self-triggering capability)

Calibration of SKIROC

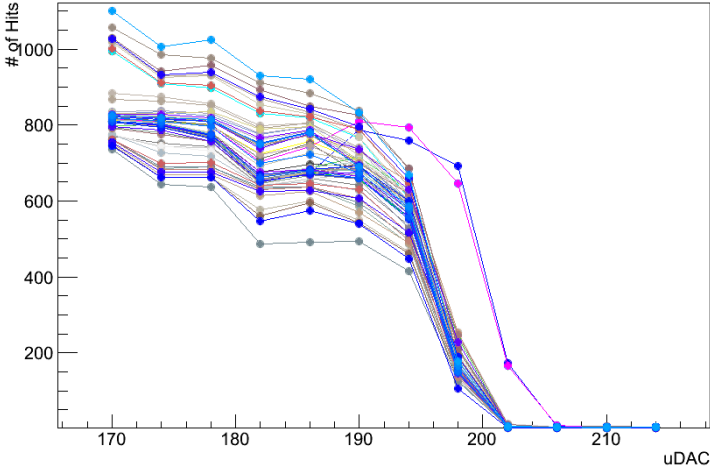
Establishment of calibration procedure for a large number of cells

Trigger threshold
- depends on the gain

- Individual channel threshold adjustment
- Range too small → R to increase current in the 4-bits DAC adjustment

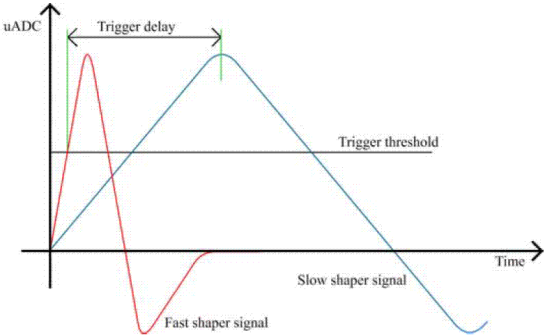


S-Curves for all the channels

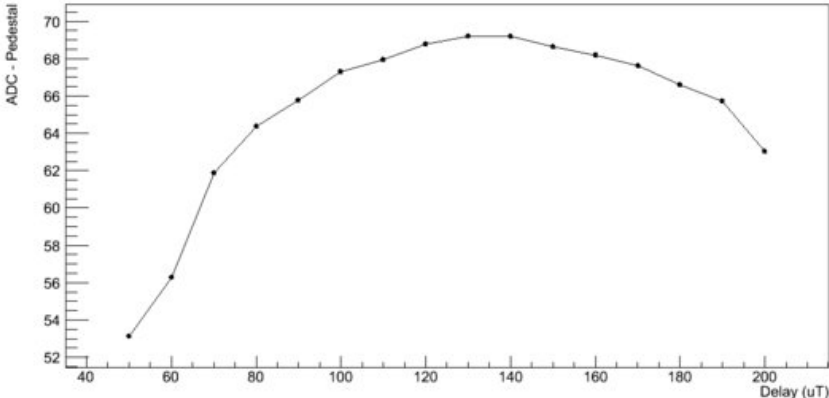


OK on test bench → to be tested in beam (need new calibration procedure)

Trigger delay



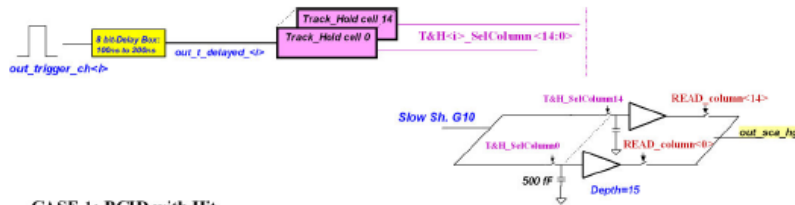
Holdscan - All SCA - Pedestal corrected



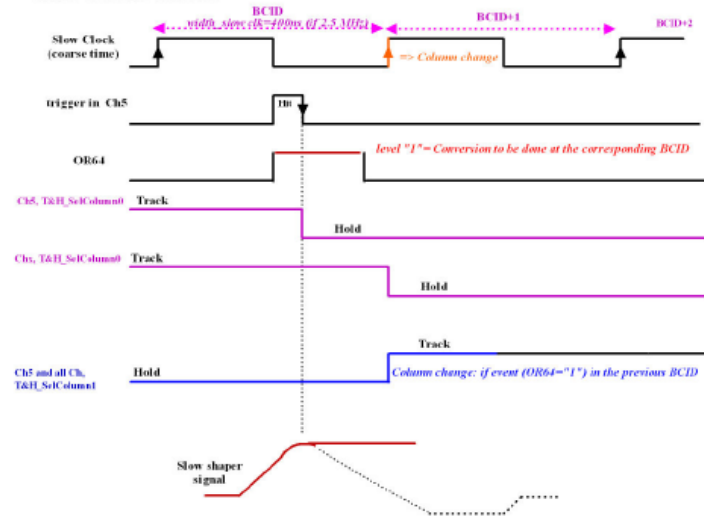
BCID+1 effect

Retriggering of the ASIC without hit

- Understood (see Nathalie and Stéphane talks)
- ~13% of the events (for $T_{\text{slowclock}} = 2.5 \text{ MHz}$):
 - Calculated: $T_{\text{slowclock}} / T_{\text{nor64}}$
 - Measured with test bench and test beam
- Easy to cut off-line

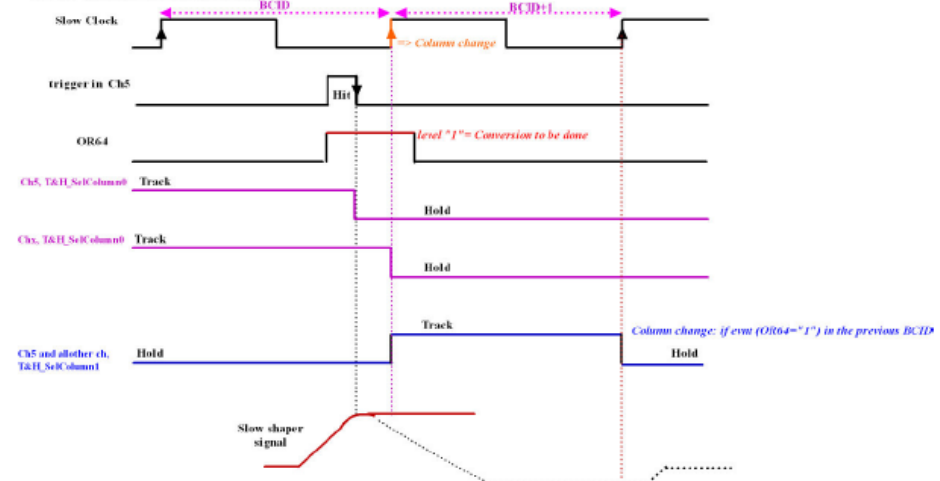


CASE 1: BCID with Hit



Conversion: BCID with one hit, SCA0 ch5: holded value= peak of the signal, other SCA0= holded value=pedestal, other SCAI= pedestal
BCID+1: No conversion because OR64 level=0 during this BCID+1

CASE 2: BCID+1 without Hit



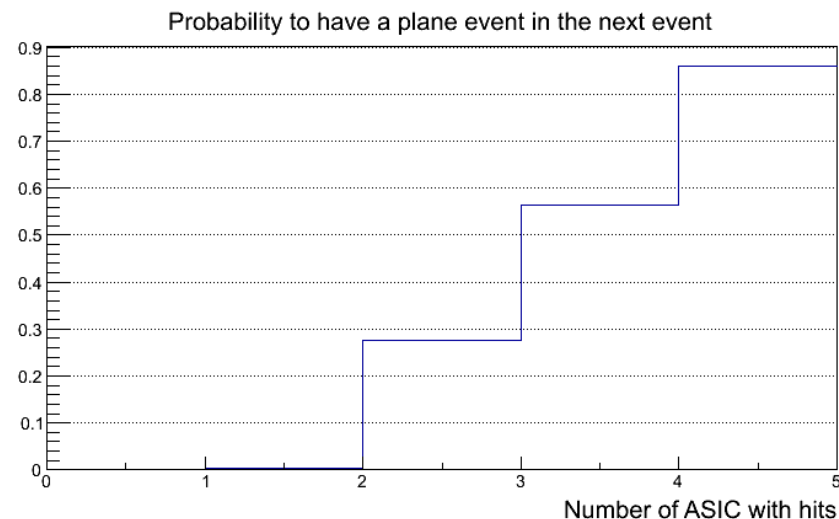
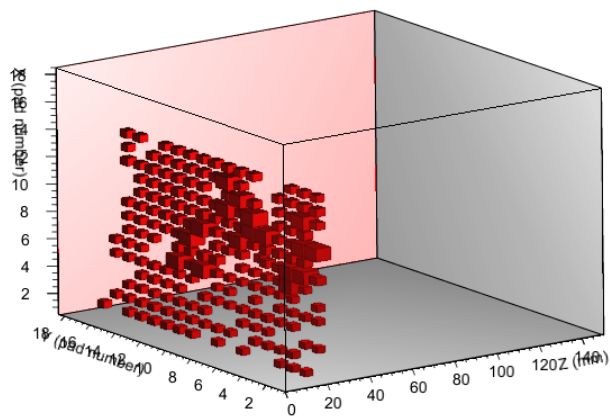
Conversion: BCID, one hit, SCA0 ch5: holded value= peak of the signal, other SCA0= holded value=pedestal
BCID+1, no hit, SCAI ch5 holded value=value < pedestal or pedestal, other SCAI holded value=ped.

Plane events

PA is referenced to the analog power supply level

Instabilities of power supply level → fake events

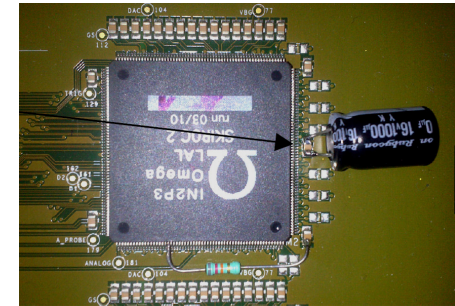
- VDD_delay/sca plugged on analog power supply → increase instabilities of power supply level
- Analog power supply common to the 4 ASIC
- Self-sustained → sometimes filled all the 15 ASIC memories
- Highly dependant of the number of ASIC with hits, dependant of the number of triggered channels



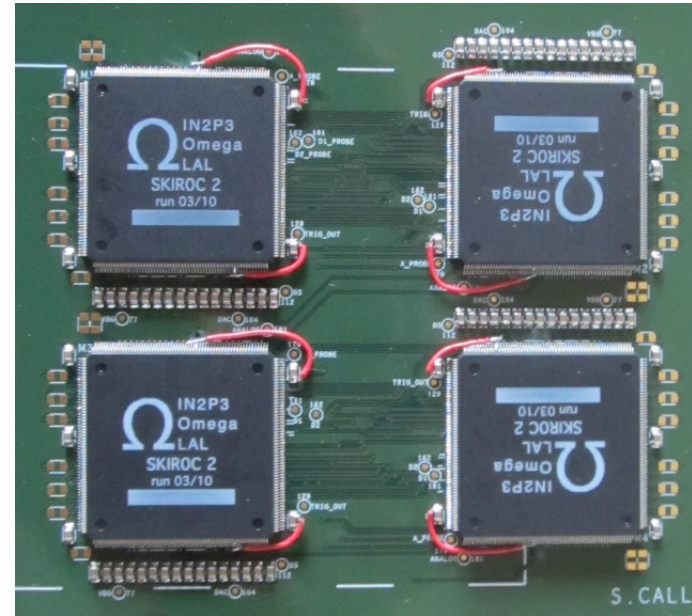
Plane events

Proposed patches

- Bigger capacitance close to the ASIC to stabilize power supply
- 2 power supply lines: Modify VDD_delay/sca routing to protect PA power supply (pin-clipping)



- 2 power supply lines: Modify VDD_delay/sca routing to protect PA power supply (pin-clipping)



First tests on test bench:

- Injection in the 4 ASICs
- Reduction of the plane events: $\sim 80\% \rightarrow \sim 10\%$ (both capa and pin-clipping)

2 slabs modified to be tested during the last test beam

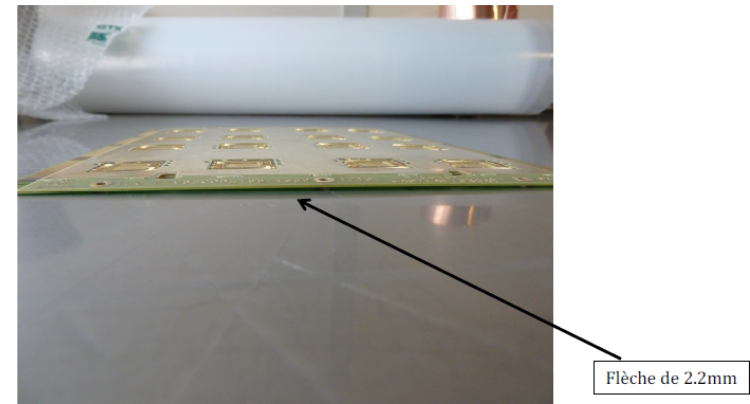
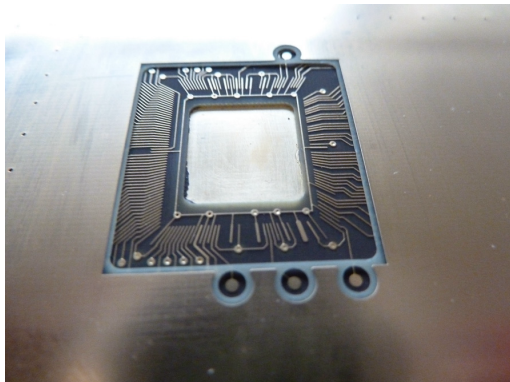
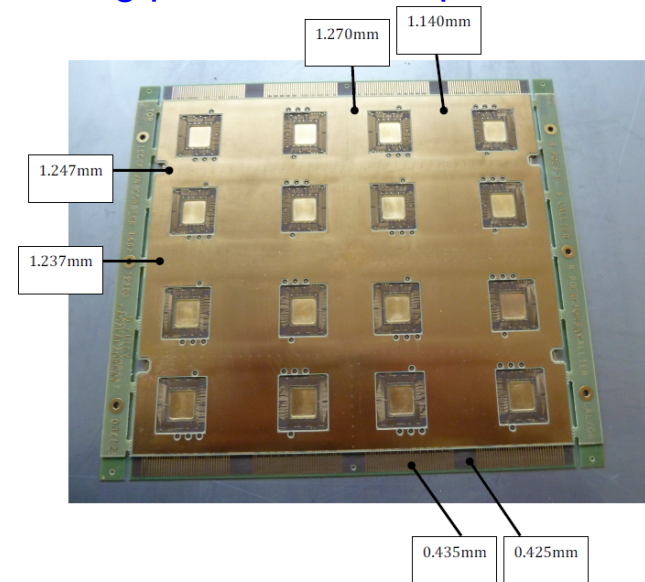
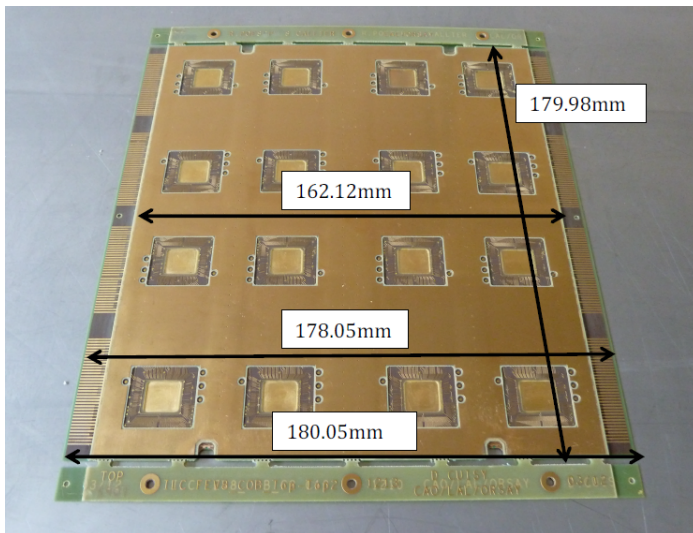
- 1 slab with big capa
 - 1 slab with pin-clipping
- see Vladik and Yuji talks

PCB

PCB is critical → Goal :1 mm thick, 8 layers, 1% flatness , ASICs bounded into

FEV COB

- Available since december 2012 (Boards from Exception and Protecno)
- First board for 16 ASICs (btw. Several proposal to assure planarity exist)
- Now equipped with 8 SKIROC ASICs (Boncing by CERN) → Needs testing
- However, bonding was not straightfoward, thin bonding pads can be improved

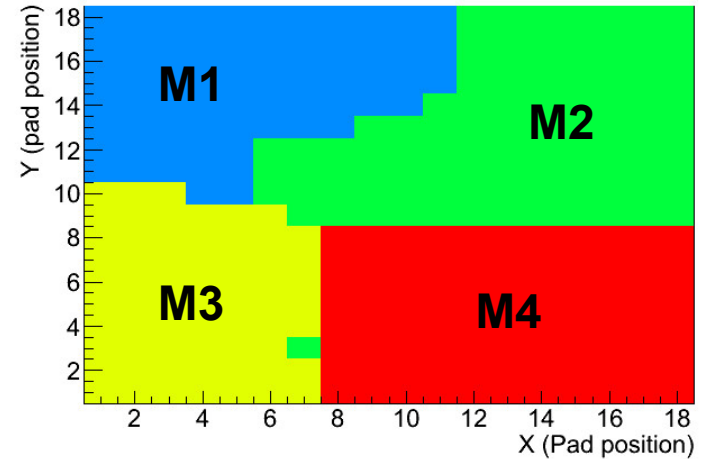
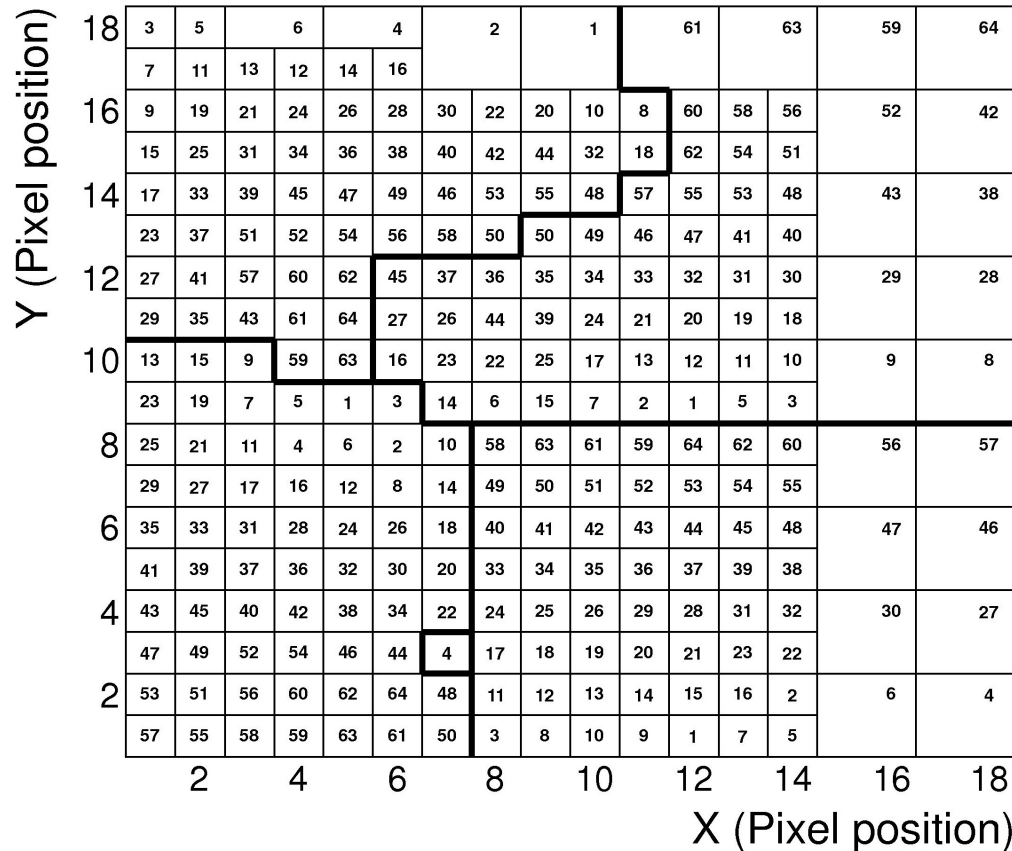


PCB

PCB is critical → Goal :1 mm thick, 8 layers, 1% flatness , ASICs bounded into
Current: FEV8 Chip in package, 1.4 mm thick

Line density in PCB → routing is crucial

- Noise
- Cross talk (Digital / readout channels → readout channels)



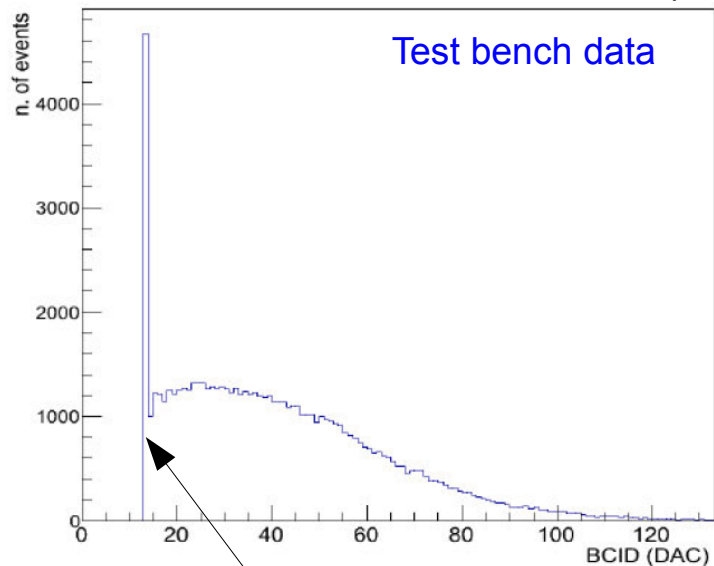
Switched off channels

Noisy channels + no individual channel adjustment → channels linked to several pixels

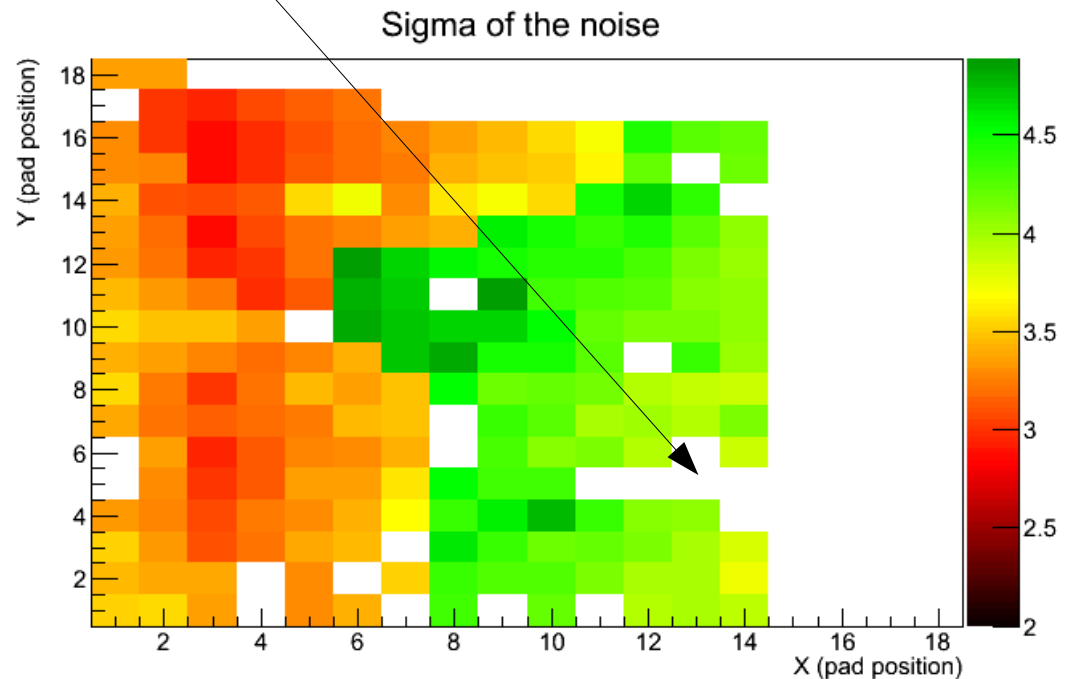
Cross talk with digital lines (valEvt, startAcq, clocks, injection line):

e.g.: ValEvt line close to M4 35-37: signal > 1 MIP

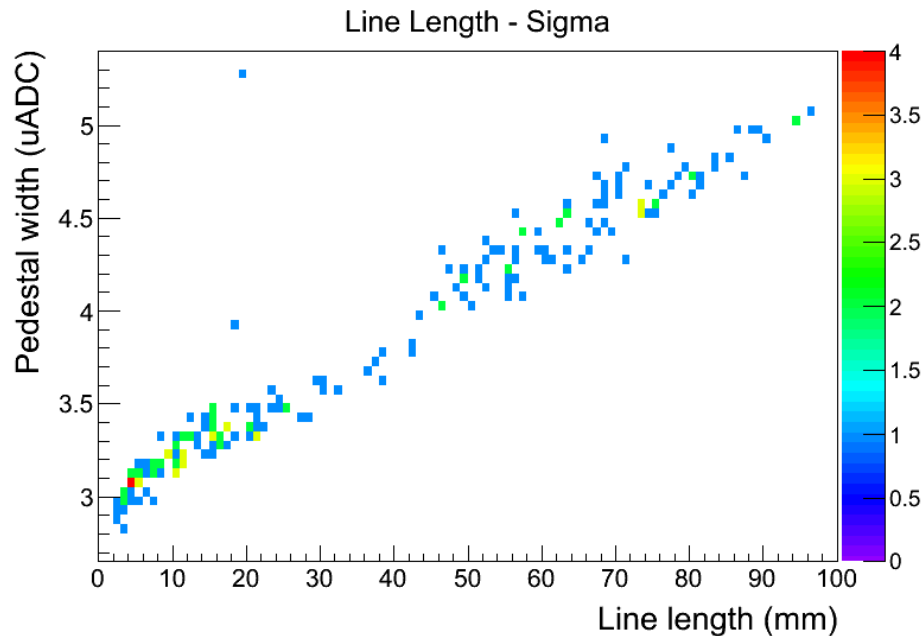
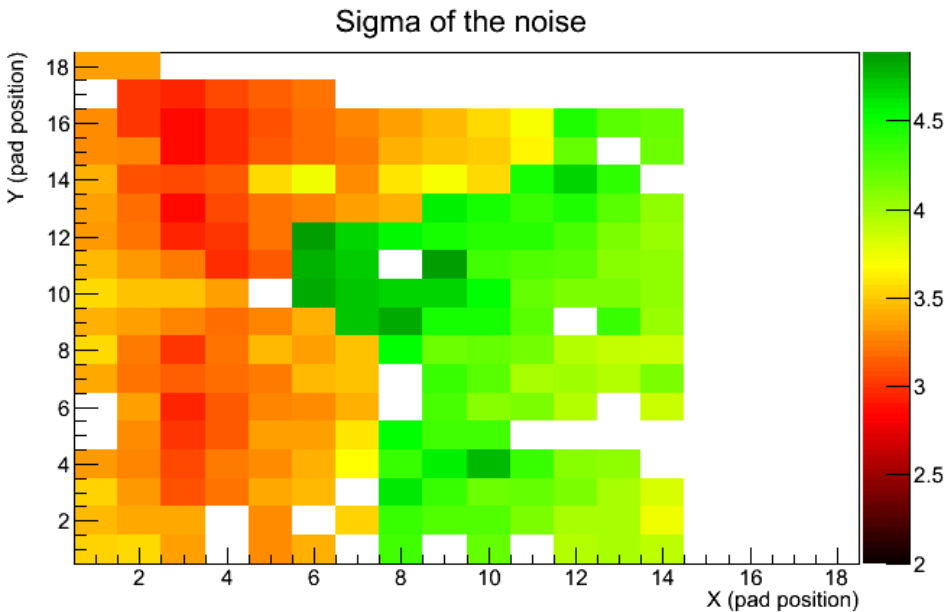
BCID distribution in channel 35 (M4)



Synchronized with
valEvt signal (13 BCID)



Noise studies



Noise \propto Line length

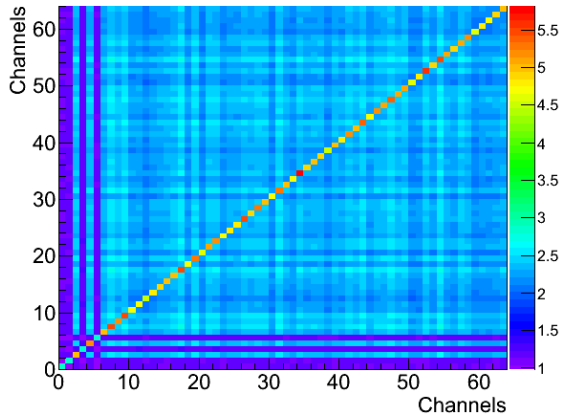
Already improved for the 16 ASIC version of the PCB

Coherent noise (general behavior)

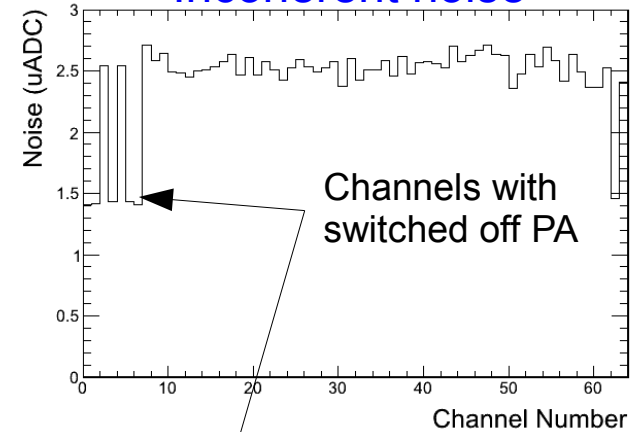
Development of algorithm to identify coherent noise (continuation of Roman studies)

e.g. : chip M1

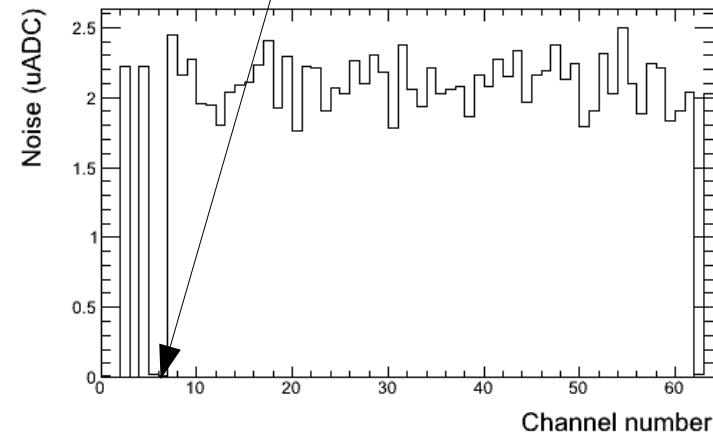
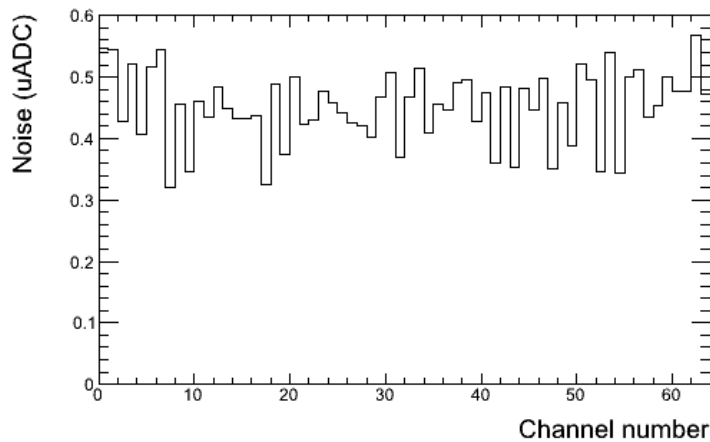
We extract incoherent noise + 2 sources of coherent noise:



Incoherent noise



Coherent noises



Common to all channels:

- Due to the ramp? (Omega expects ~ 0.5 ADC)

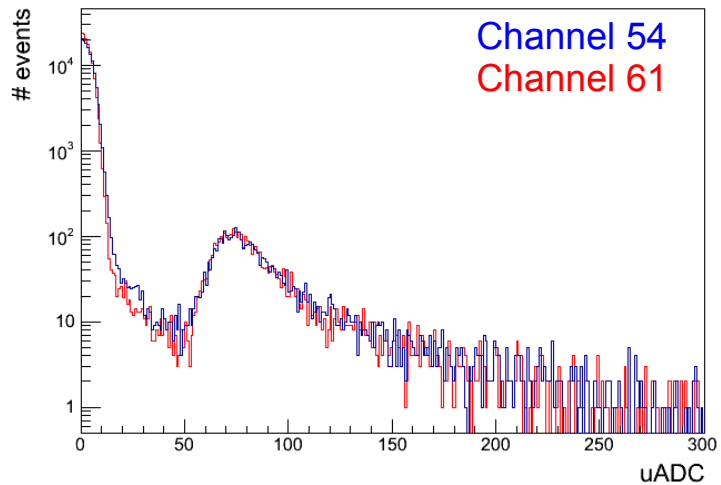
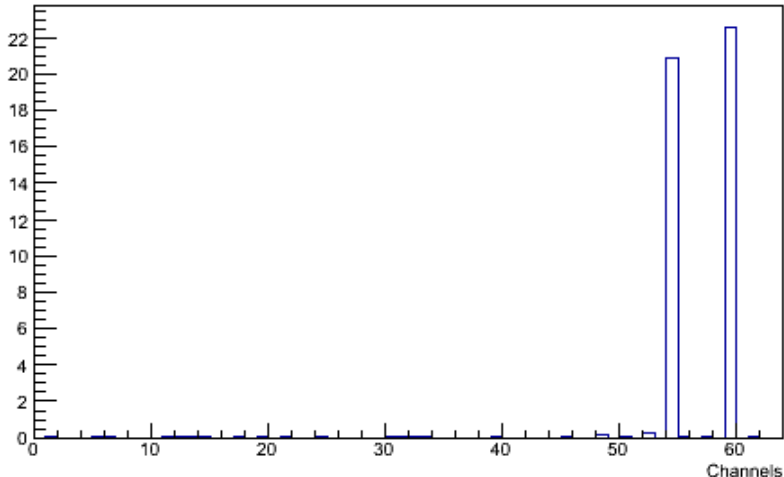
Common to channels with switched on PA:

- Due to PA?
- To be clearly identified and reduced (if possible): under discussion with experts (Omega)

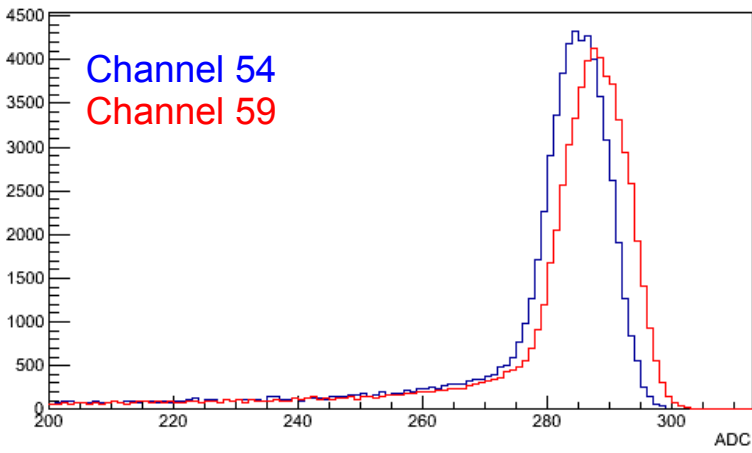
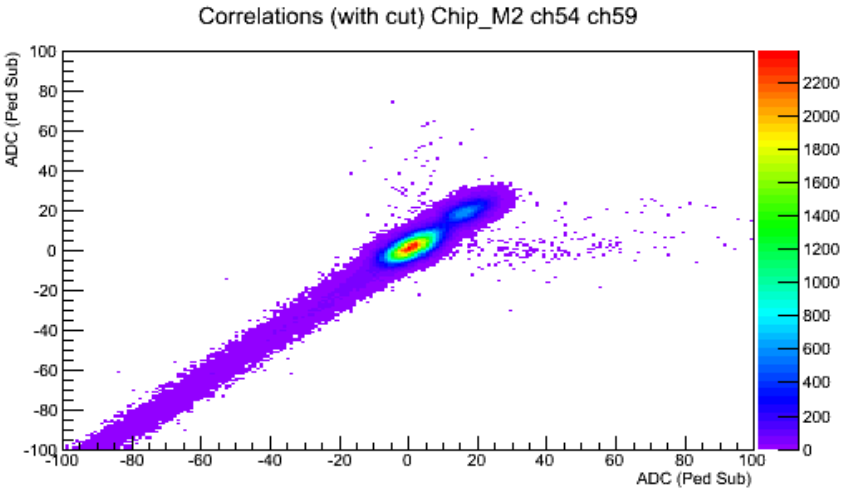
Correlation studies

Chip M2 (all layers):

- Another coherent noise source → 2 highly correlated channels
- No clear idea of the source



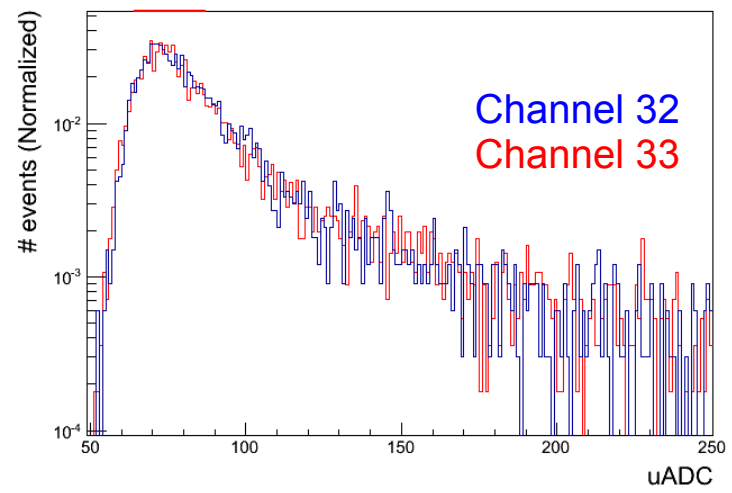
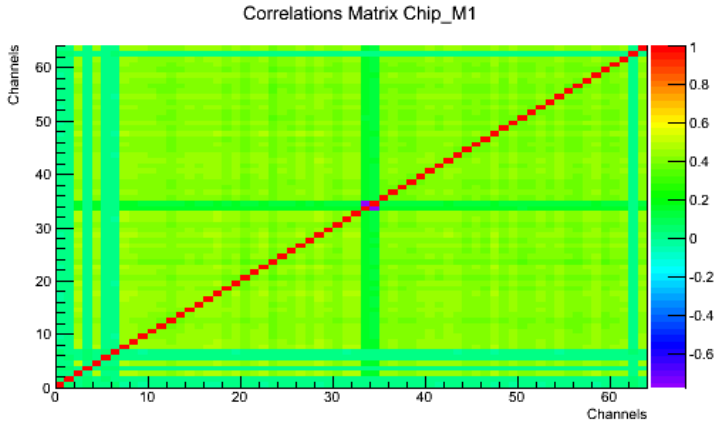
We don't see an effect on MIP distribution



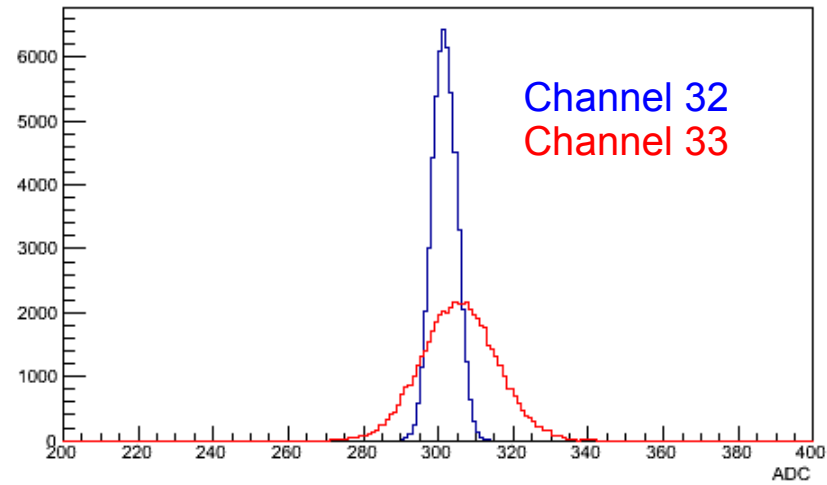
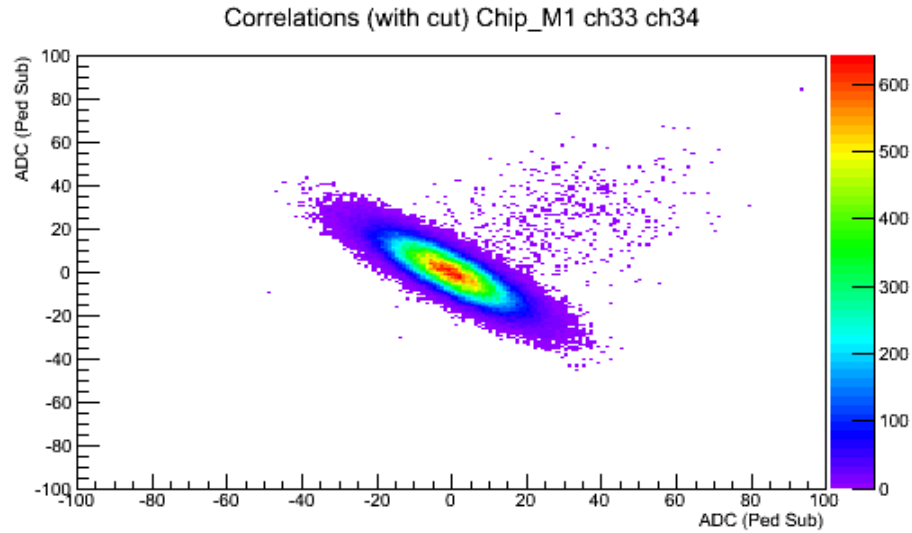
Correlation studies

Chip M1 (only in slab3) :

- Another coherent noise source \rightarrow 2 highly anti-correlated channels
- No clear idea of the source of this behavior

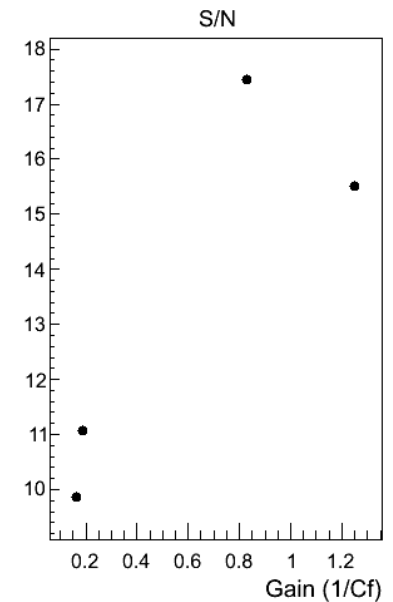
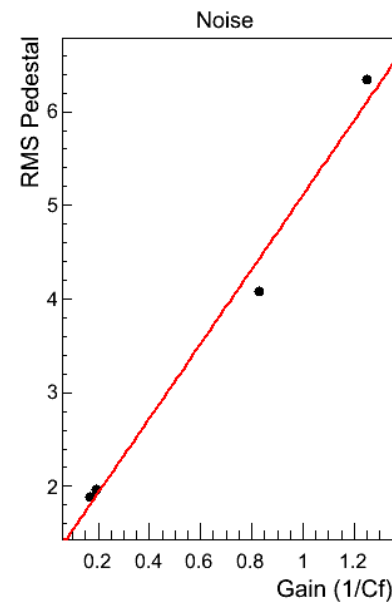
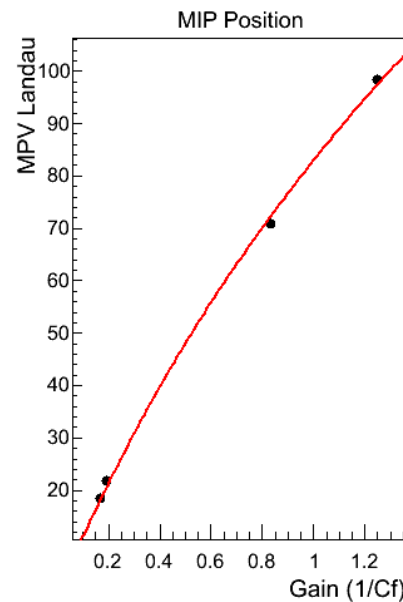
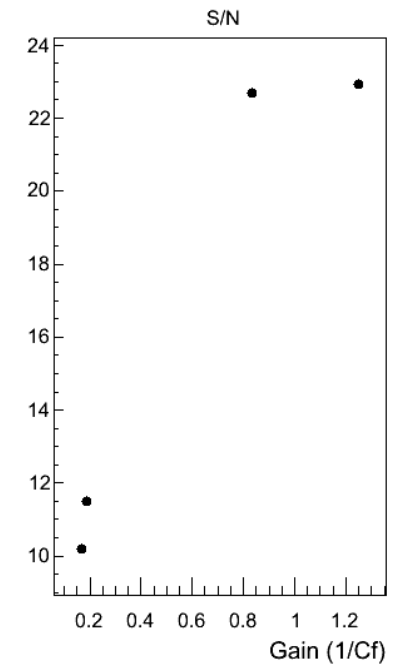
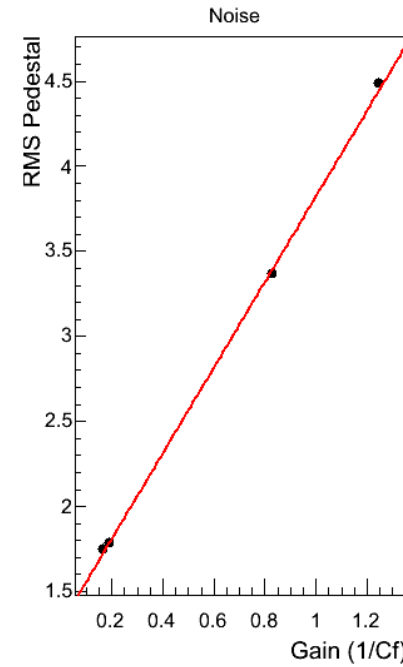
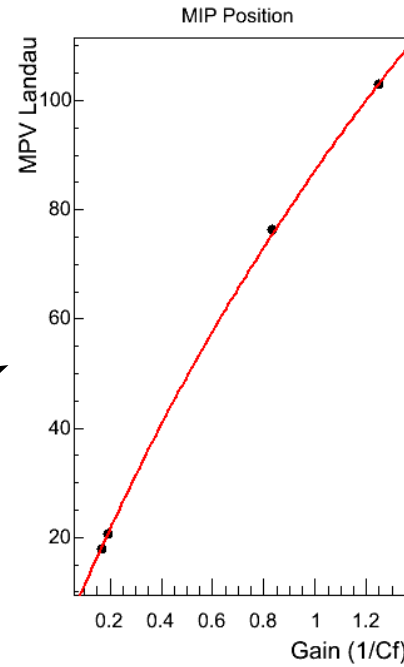
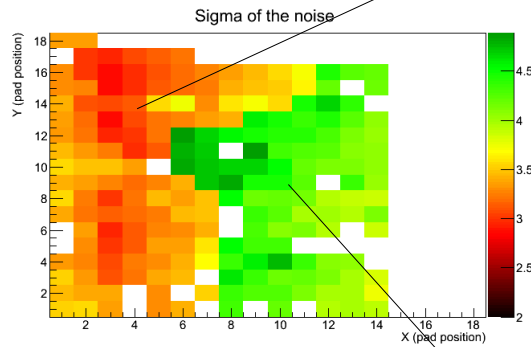


We don't see an effect on MIP distribution.
We should check the S/N ration @ low gain



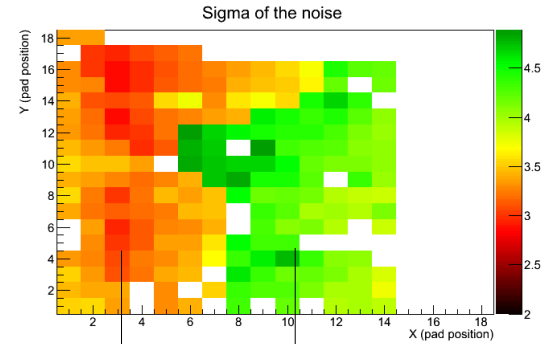
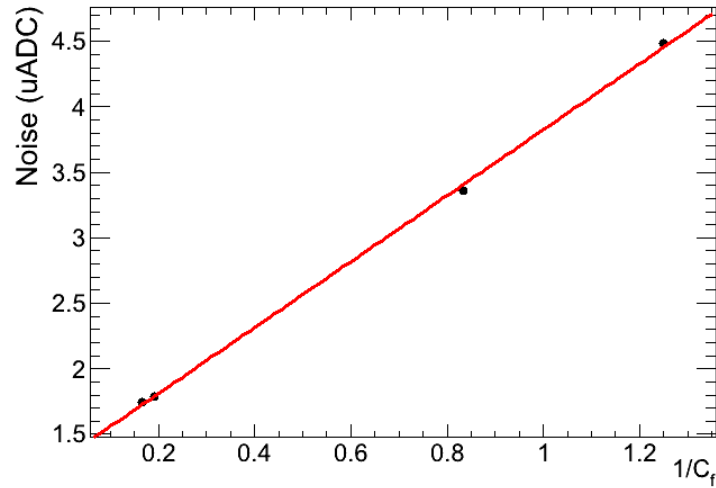
SKIROC results as a function of the gain

$$\text{Gain} \propto 1/C_f$$

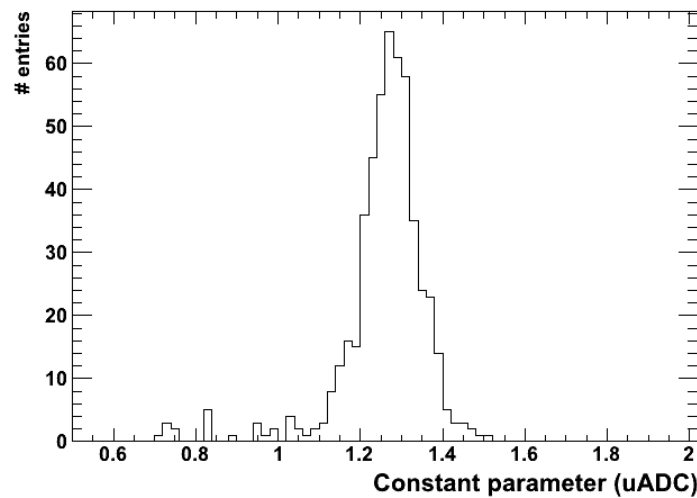


Saturation of the MIP position → bad holdscan calibration?

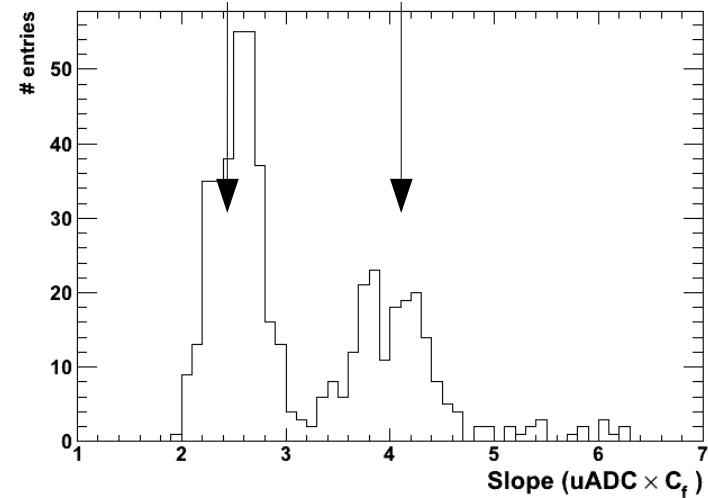
Fit of the noise as a function of the gain



Constant parameter of the linear fit
for all channels / ASICs / Slabs

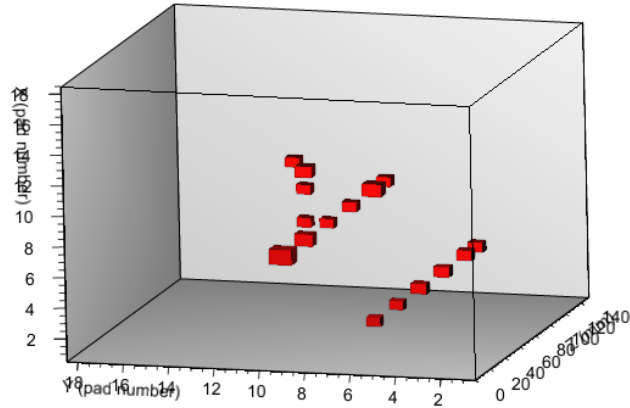


Slope of the linear fit for all
channels / ASICs / Slabs

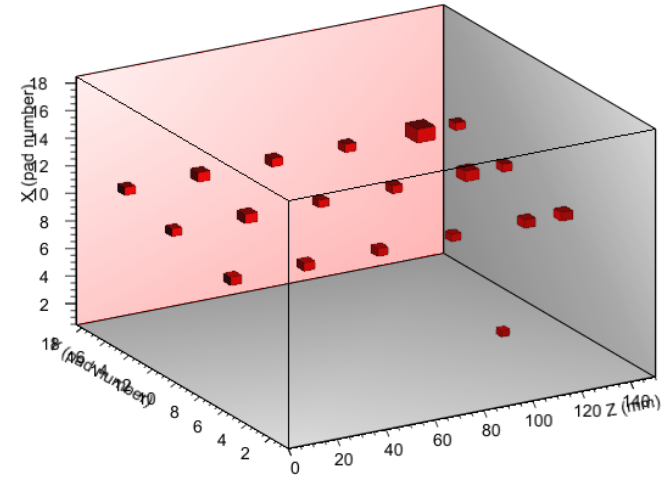


Event display

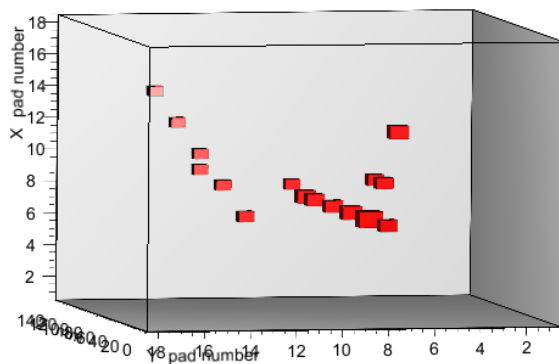
2 e- (3 GeV, no tungsten)



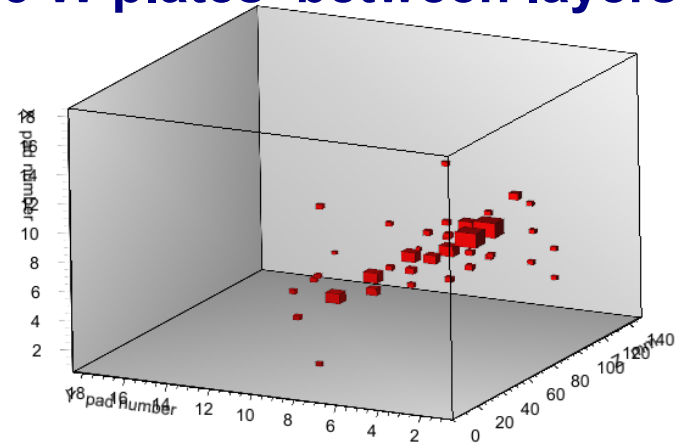
3 e- (3 GeV, no tungsten)



1 cosmic + 1 e- (3 GeV, no tungsten)



**1 e- (5 GeV)
5 W plates between layers**



Summary

2012 test beams have provided useful data.

Mainly thanks to the Frédéric's work on DAQ software

Major step forward in the understanding of the detector

BCID+1

Plane events

Switched off channels due to crosstalk with digital line or readout channels

Noise structure

To be continued with power pulsing studies

See Nathalie, Vladik and Yuji talks

R&D in progress... first test beam shows promising results